Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package name	Standard dimensions mm (inch)	Not Mounted
1	C1	1	0.1 µF	ECWF6104JL	Panasonic	Film, 630 V, ±5 %		Through Hole	
2	C2	1	0.22 µF			Ceramic, 50 V, ±10 %		1.6 x 0.8 (0603)	
3	C3, C18, C43, C49, C50	5	1000 pF			Ceramic, 50 V, ±10 %		1.6 x 0.8 (0603)	
4	C4	1	10000 pF			Ceramic, 630 V, ±10 %		3.2 x 1.6 (1206)	
5	C5	1	1 µF	LE105-M	OKAYA	Polypropylene Film, 275 VAC, ±10 %		Through Hole	
6	C6, C7	2	3300 pF			Ceramic, 50 V, ±10 %		1.6 x 0.8 (0603)	
7	C8, C25	2	2.2 µF			Ceramic, 50 V, ±10 %		1.6 x 0.8 (0603)	
8	C9, C12	2	0.22 µF	LE224-MX	OKAYA	Polypropylene Film, 310 VAC, ±10 %		Through Hole	
9	C10, C17, C20, C33, C40, C64, C65	7	0.1 µF			Ceramic, 50 V, ±10 %		1.6 x 0.8 (0603)	
10	C11	1	22 µF			Aluminum Electrolytic, 50 V, ±20 %		Through Hole	
11	C13, C15, C47	3	2200 pF	DE1E3KX222MN5AA01	MURATA	Disc Ceramic, 250 VAC, ±10 %		Through Hole	
12	C14	1	4.7 µF			Ceramic, 50 V, ±10 %		3.2 x 1.6 (1206)	
13	C16, C34	2	0.22 µF			Ceramic, 50 V, ±10 %		1.6 x 0.8 (0603)	
14	C19, C38, C54, C58	4	1 µF			Ceramic, 50 V, ±10 %		1.6 x 0.8 (0603)	
15	C21	1	470 pF			Ceramic, 50 V, ±5 %		1.6 x 0.8 (0603)	
16	C22	1	220 µF			Aluminum Electrolytic, 25 V, ±20 %		Through Hole	
17	C23	1	1.0 µF	ECWFD2W105K	Panasonic	Film, 450 V, ±10 %		Through Hole	
18	C24	1	0.1 µF	MMX0450K104	Nissei	Film, 450 V, ±10 %		Through Hole	
19	C26, C28	2	220 pF			Ceramic, 50 V, ±5 %		1.6 x 0.8 (0603)	
20	C27	1	10 pF			Ceramic, 50 V, ±5 %		1.6 x 0.8 (0603)	
21	C29	1	22 µF			Ceramic, 25 V, ±20 %		3.2 x 2.5 (1210)	
22	C30	1						1.6 x 0.8 (0603)	Not Mounted
23	C31, C32	2	330 µF			Aluminum Electrolytic, 450 V, ±20 %		Through Hole	
24	C35	1	470 pF			Ceramic, 50 V, ±10 %		1.6 x 0.8 (0603)	
25	C36, C37, C39, C53, C55	5	2.2 µF			Ceramic, 50 V, ±10 %		2.0 x 1.2 (0805)	

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package name	Standard dimensions mm (inch)	Not Mounted
26	C41, C78	2	56 µF			Aluminum Electrolytic, 35 V, ±20 %		Through Hole	
27	C42, C45	2	0.047 µF	ECWF6473JL	Panasonic	Film, 630 V, ±5 %		Through Hole	
28	C44	1	100 pF			Ceramic, 1 kV, ±5 %		3.2 x 1.6 (1206)	
29	C46	1	150 pF			Ceramic, 1000 V, ±5 %		3.2 x 1.6 (1206)	
30	C51	1	0.01 µF			Ceramic, 50 V, ±5 %		1.6 x 0.8 (0603)	
31	C52	1	4700 pF			Ceramic, 50 V, ±5 %		1.6 x 0.8 (0603)	
32	C56, C57, C59, C60, C61, C62, C63, C66, C67, C69	10	560 µF		Panasonic	Aluminum Organic Polymer, 16 V, ±20 %		Through Hole	
33	C68	1	0.01 µF			Ceramic, 50 V, ±10 %		1.6 x 0.8 (0603)	
34	C70	1	10 µF			Ceramic, 50 V, ±10 %		3.2 x 2.5 (1210)	
35	C71, C72, C74, C75, C76, C77	6	22 µF			Ceramic, 25 V, ±20 %		2.0 x 1.2 (0805)	
36	C73	1	2200 pF			Ceramic, 50 V, ±10 %		1.6 x 0.8 (0603)	
37	C79	1	0.01 µF			Film, 630 V, ±10 %		Through Hole	
38	C80, C81	2	2.2 µF			Ceramic, 25 V, ±10 %		1.6 x 0.8 (0603)	
39	D1, D2, D13	3	-	CRG04A	TOSHIBA	General Purpose Diode	S-FLAT	1.6 x 3.5	
40	D3, D4, D5, D7, D11, D12, D17, D19, D24, D25, D26	11	-	1SS187	TOSHIBA	Switching Diode	S-Mini	2.9 x 2.5	
41	D6, D22	2	-	CRF03A	TOSHIBA	Fast Recovery Diode	S-FLAT	1.6 x 3.5	
42	D8, D14	2	-	CRH01	TOSHIBA	High Efficiency Diode	S-FLAT	1.6 x 3.5	
43	D9, D16, D20, D21	4	-	CRS04	TOSHIBA	Schottky Barrier Diode	S-FLAT	1.6 x 3.5	
44	D10	1	-	D25XB60-7000	SHINDENGEN	Diode Bridge		Through Hole	
45	D15	1	-	S3V60	SHINDENGEN	Diode Bridge		Through Hole	
46	D18	1		(TRS6V65H) Under development	TOSHIBA	SiC Schottky Barrier Diode	DFN8x8	8 x 8	
47	D23	1	-	CRS13	TOSHIBA	Schottky Barrier Diode	S-FLAT	1.6 x 3.5	
48	F1	1	10A	FSL250V10AEM	Nippon Seisen	250V			
49	HS	1		15FP23-L65	LSI	Heat Sink		Through Hole	
50	HS2	1		HTE30-20(3)-60	Mizutani Electric	Heat Sink		Through Hole	
51	HS3	1		38SQ38H10	LSI	Heat Sink		Through Hole	

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package name	Standard dimensions mm (inch)	Not Mounted
52	HS4	1		15FP23-L50	LSI	Heat Sink		Through Hole	
53	L1, L2	2	5 mH	ADR-25-07-050T	UENO	Choke Coil		Through Hole	
54	L3	1	335 μH	BCH20W-10335Y	UENO	Inductor		Through Hole	
55	PC1	1	-	TLP385(GR	TOSHIBA	Photocoupler	4pin SO6L	3.8 x 7.5	
56	Q1	1	-	RN2402	TOSHIBA	Transistor	S-Mini	2.9 x 1.5	
57	Q2, Q3, Q4, Q5	4	-	RN1402	TOSHIBA	Transistor	S-Mini	2.9 x 2.5	
58	Q6	1	-	TK090U65Z	TOSHIBA	MOSFET	TOLL	11 x 10	
59	Q7, Q8	2	-	TK20A60W5	TOSHIBA	MOSFET	TO-220SIS	Through Hole	
60	Q10, Q11, Q12, Q13	4	-	TPH1R306P1	TOSHIBA	MOSFET	SOP Advance	5.0 x 6.0	
61	Q14, Q15, Q16	3	-	TPHR9203PL	TOSHIBA	MOSFET	SOP Advance	5.0 x 6.0	
62	R1	1	120 k			1/10 W, ±5 %		1.6 x 0.8 (0603)	
63	R2, R3, R4	3	220 k			1/4 W, ±5 %		3.2 x 1.6 (1206)	
64	R5	1	39 k			1/10 W, ±5 %		1.6 x 0.8 (0603)	
65	R6, R7	2	270 k			1/4 W, ±10 %		3.2 x 1.6 (1206)	
66	R8	1	2.7 k			1/10 W, ±1 %		1.6 x 0.8 (0603)	
67	R9	1	1 M			1/10 W, ±5 %		1.6 x 0.8 (0603)	
68	R10, R11	2	82 k			1/4 W, ±5 %		3.2 x 1.6 (1206)	
69	R12, R14, R98, R99, R113, R115, R116	7	10			1/8 W, ±5 %		1.6 x 0.8 (0603)	
70	R13, R70, R72, R85	4						1.6 x 0.8 (0603)	Not Mounted
71	R15	1	100			1/8 W, ±5 %		1.6 x 0.8 (0603)	
72	R16, R91, R96	3	100 k			1/10 W, ±5 %		1.6 x 0.8 (0603)	
73	R17	1	470			1/8 W, ±5 %		1.6 x 0.8 (0603)	
74	R18	1	330 k			1/10 W, ±5 %		1.6 x 0.8 (0603)	
75	R19, R51, R104	3	220			1/8 W, ±5 %		1.6 x 0.8 (0603)	
76	R20	1	27 k			1/10 W, ±1 %		1.6 x 0.8 (0603)	
77	R21	1	18 k			1/10 W, ±1 %		1.6 x 0.8 (0603)	
78	R22, R102	2	2.2 k			1/10 W, ±5 %		1.6 x 0.8 (0603)	

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package name	Standard dimensions mm (inch)	Not Mounted
79	R23	1	47 k			1/10 W, ±1 %		1.6 x 0.8 (0603)	
80	R24, R25, R28, R30, R31, R49, R75, R81, R82, R97	10	10 k			1/10 W, ±5 %		1.6 x 0.8 (0603)	
81	R26	1	22			1/8 W, ±5 %		1.6 x 0.8 (0603)	
82	R27	1	22 k			1/10 W, ±5 %		1.6 x 0.8 (0603)	
83	R29	1	36 k			1/10 W, ±5 %		1.6 x 0.8 (0603)	
84	R32	1	56			1/8 W, ±1 %		1.6 x 0.8 (0603)	
85	R33	1	150			1/4 W, ±5 %		3.2 x 1.6 (1206)	
86	R34, R35	1	5.1	A5MC-5R1JK L3.5	Uchihashi Estec	2.1 W, ±5 %		Through Hole	
87	R36, R37, R38	3	150 k			1/10 W, ±0.5 %, ±25 ppm		2.0 x 1.2 (0805)	
88	R39	1	130 k			1/10 W, ±0.5 %, ±25 ppm		2.0 x 1.2 (0805)	
89	R40	1	120 k			1/10 W, ±0.5 %, ±25 ppm		2.0 x 1.2 (0805)	
90	R41	1	9.1 k			1/10 W, ±0.5 %		1.6 x 0.8 (0603)	
91	R42	1	2.2			1/4 W, ±5 %		3.2 x 1.6 (1206)	
92	R43, R44, R45	3	68 m			1 W, ±1 %		3.2 x 1.6 (1206)	
93	R46	1	10			1/4 W, ±5 %		3.2 x 1.6 (1206)	
94	R47, R84, R105	3	4.7 k			1/10 W, ±5 %		1.6 x 0.8 (0603)	
95	R48, R59, R60	3	10 k			1/10 W, ±1 %		1.6 x 0.8 (0603)	
96	R50	1	470 k			1/10 W, ±5 %		1.6 x 0.8 (0603)	
97	R52, R53, R54, R55, R56	5	180 k			1/4 W, ±1 %		2.0 x 1.2 (0805)	
98	R57	1	9.1 k			1/10 W, ±1 %		1.6 x 0.8 (0603)	
99	R58	1	22K	RK73G2ATTD2202D	KOA	Resistor, 1/8W, ± 0.5%		2.0 x 1.25 (805)	
100	R58	1	22 k			1/8 W, ±0.5 %		2.0 x 1.2 (0805)	
101	R61	1	1 k			1/8 W, ±1 %		1.6 x 0.8 (0603)	
102	R62	1	3.3 k			1/10 W, ±1 %		1.6 x 0.8 (0603)	
103	R63, R64, R65, R66, R67	5	470 k			1/8 W, ±0.5 %		2.0 x 1.2 (0805)	

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package name	Standard dimensions mm (inch)	Not Mounted
104	R68	1	27 k			1/8 W, ±0.5 %		2.0 x 1.2 (0805)	
105	R69	1	68 k			1/10 W, ±1 %		1.6 x 0.8 (0603)	
106	R71	1	43 k			1/10 W, ±1 %		1.6 x 0.8 (0603)	
107	R73, R103, R117	3	0			1/10 W		1.6 x 0.8 (0603)	
108	R74, R76	2	0			1/4 W		3.2 x 1.6 (1206)	
109	R77, R78	2	47			1/4 W, ±5 %		3.2 x 1.6 (1206)	
110	R79	1	750 k			1/10 W, ±1 %		1.6 x 0.8 (0603)	R79
111	R80	1	360 k			1/10 W, ±1 %		1.6 x 0.8 (0603)	
112	R83	1	2.2			1/8 W, ±5 %		1.6 x 0.8 (0603)	
113	R86	1	200			1/8 W, ±5 %		1.6 x 0.8 (0603)	
114	R88, R89	2	4.7			1/4 W, ±5 %		3.2 x 1.6 (1206)	
115	R92, R93, R94, R95	4	0			2 A		3.2 x 1.6 (1206)	
116	R100	1	3.3 k			1/10 W, ±5 %		1.6 x 0.8 (0603)	
117	R101	1	3.9 k			1/10 W, ±5 %		1.6 x 0.8 (0603)	
118	R106	1	150			1/8 W, ±1 %		1.6 x 0.8 (0603)	
119	R107	1	8.2 k			1/10 W, ±0.5 %		1.6 x 0.8 (0603)	
120	R108	1	2.2 k			1/10 W, ±0.5 %		1.6 x 0.8 (0603)	
121	R109, R110, R111, R112	4	100			1/4 W, ±5 %		3.2 x 1.6 (1206)	
122	R114	1	1 k			1/8 W, ±5 %		1.6 x 0.8 (0603)	
123	RL1	1	DC12V	G5CA-1A-DC12V	OMRON	DC12 V, 10 A		Through Hole	
124	T1	1	-	TR072-132-0	PAT			Through Hole	
125	T2	1	-	TR071-132-0	PAT			Through Hole	
126	TB1	1	-	OTB-771N-BL-3P	Osada	300 v, 24 A			
127	TB2	1	-	OTB-781N-B-4P	Osada	250 V, 24A			
128	TH1	1	-	EC2F103A2-40113	SEMITEC	10 kΩ±1 %, 3435K		Through Hole	
129	U1, U4	2	-	TA75W393FU	TOSHIBA		SM8	2.9 x 4.0	
130	U2, U3	2	-	UCC28910D	Texas Instruments			3.9 x 4.9	
131	U5	1	-	UCC256303-3DDB	Texas Instruments			9.9 x 3.9	
132	U6	1	-	NJM2904M	NJRC			5 x 5	

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package name	Standard dimensions mm (inch)	Not Mounted
133	U7, U10	2	-	TL431LIBIDBZR	Texas Instruments			2.9 x 1.3	
134	U8, U9	2	-	UCC24612-2DBV	Texas Instruments			2.9 x 1.55	
135	U11	1	-	TPS2412D	Texas Instruments			3.9 x 4.9	
136	VAR1	1	680 V	ERZV10D681	Panasonic			Through Hole	
137	ZD1	1	6.8 V	CRY68	TOSHIBA		S-FLAT	1.6 x 3.5	
138	ZD2	1	6.2 V	CRY62	TOSHIBA		S-FLAT	1.6 x 3.5	
139	ZD3	1	-				S-FLAT	1.6 x 3.5	Not Mounted

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